

PS2501-1, -4, PS2501L-1, -4

R08DS0202EJ0200

Rev.2.00

HIGH ISOLATION VOLTAGE SINGLE TRANSISTOR TYPE

Jun. 16, 2026

DESCRIPTION

The PS2501-1, -4 and PS2501L-1, -4 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2501-1, -4 are in a plastic DIP (Dual In-line Package) and the PS2501L-1, -4 are lead bending type (Gull-wing) for surface mount.

FEATURES

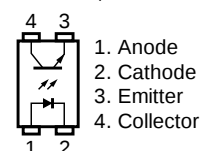
- High isolation voltage ($BV = 5\,000\text{ Vr.m.s.}$)
- High collector to emitter voltage ($V_{CE0} = 80\text{ V}$)
- High-speed switching ($t_r = 3\text{ }\mu\text{s TYP.}$, $t_f = 5\text{ }\mu\text{s TYP.}$)
- Ordering number of taping product: PS2501L-1-F3 : 2 000 pcs/reel
- Pb-free product
- Safety standards
 - UL approved: UL 1577, Double protection

APPLICATIONS

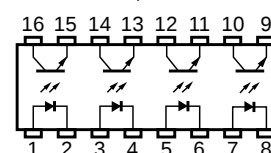
- Power supply
- Telephone/FAX.
- FA/OA equipment
- Programmable logic controller

PIN CONNECTION (Top View)

PS2501-1, PS2501L-1

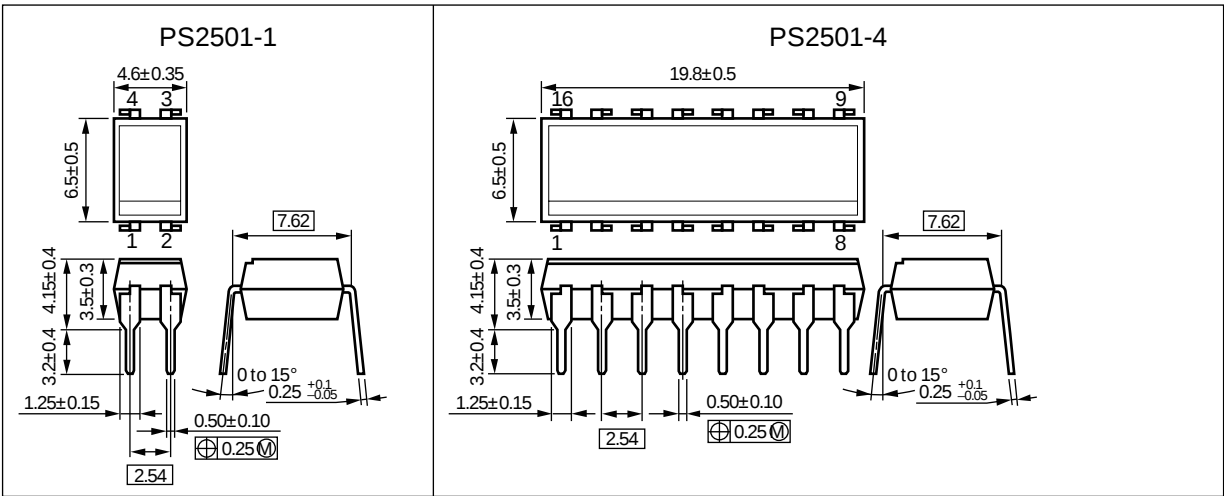


PS2501-4, PS2501L-4

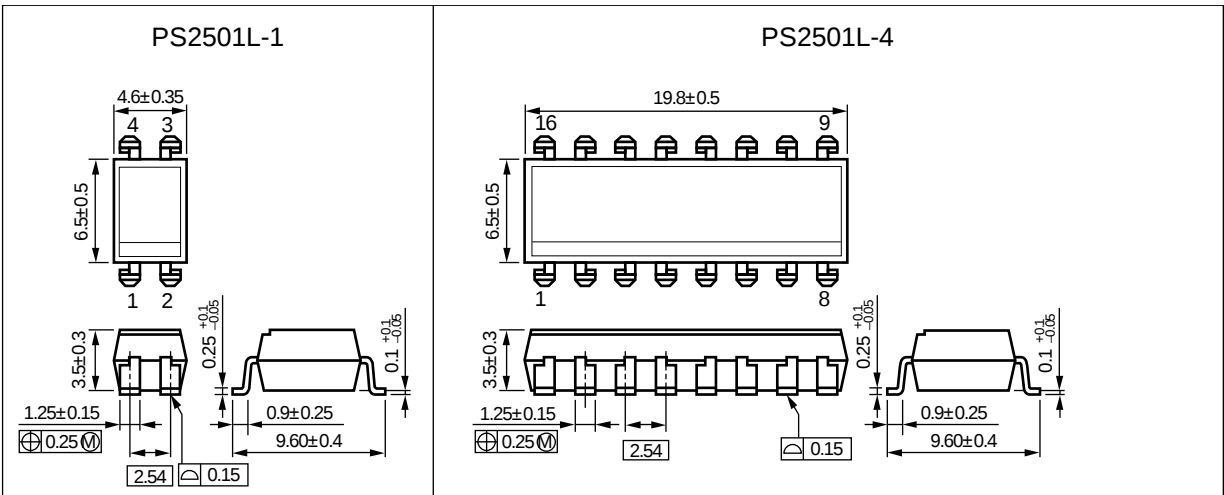


PACKAGE DIMENSIONS (UNIT: mm)

DIP Type



Lead Bending Type For Surface Mount



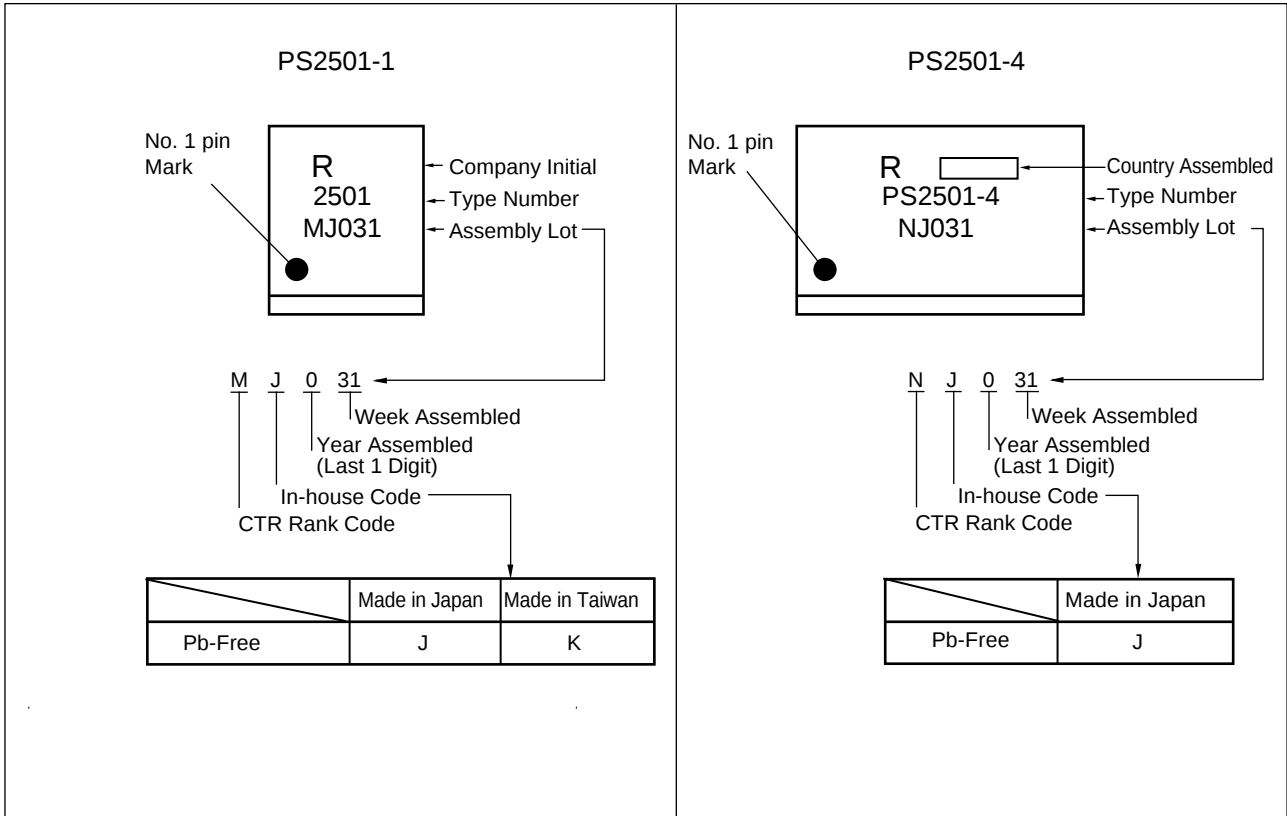
Weight (4-pin DIP) : 0.26 g (TYP.)

Weight (16-pin DIP) : 1.02 g (TYP.)

PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	7 mm
Creepage Distance	7 mm
Isolation Distance	0.3 mm

MARING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number *1	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number *2
PS2501-1	PS2501-1-A	Pb-Free	Magazine case 100 pcs	Standard products (UL Approved)	PS2501-1
PS2501L-1	PS2501L-1-A				PS2501L-1
PS2501L-1-F3	PS2501L-1-F3-A		Embossed Tape 2 000 pcs/reel		PS2501L-1
PS2501-4	PS2501-4-A		Magazine case 20 pcs		PS2501-4
PS2501L-4	PS2501L-4-A				PS2501L-4

Notes: *1. When specifying CTR rank, please add “-CTR rank” after Order Number.

ex. L rank : PS2501-1-A-L

Notes: *2. For the application of the safety standard, the following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS2501-1, PS2501L-1	PS2501-4, PS2501L-4	
Diode	Reverse Voltage	V _R	6		V
	Forward Current (DC)	I _F	80		mA/ch
	Power Dissipation Derating	ΔP _D /°C	1.5	1.2	mW/°C
	Power Dissipation	P _D	150	120	mW/ch
	Peak Forward Current *1	I _{FP}	1		A/ch
Transistor	Collector to Emitter Voltage	V _{CEO}	80		V
	Emitter to Collector Voltage	V _{ECO}	7		V
	Collector Current	I _C	50		mA/ch
	Power Dissipation Derating	ΔP _C /°C	1.5	1.2	mW/°C
	Power Dissipation	P _C	150	120	mW/ch
Isolation Voltage *2		BV	5 000		Vr.m.s.
Operating Ambient Temperature		T _A	-55 to +100		°C
Storage Temperature		T _{stg}	-55 to +150		°C

Note: *1. PW = 100 μs, Duty Cycle = 1 %

*2. AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output.
Pins 1-2 shorted together, 3-4 shorted together.

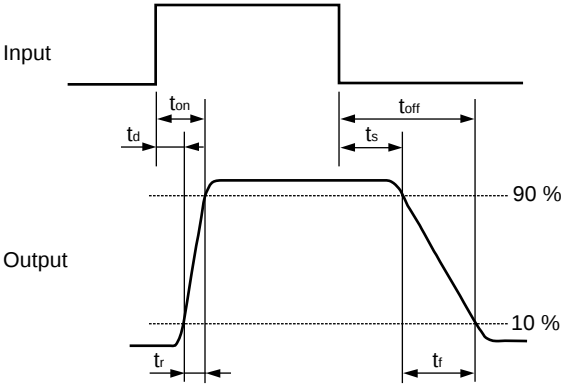
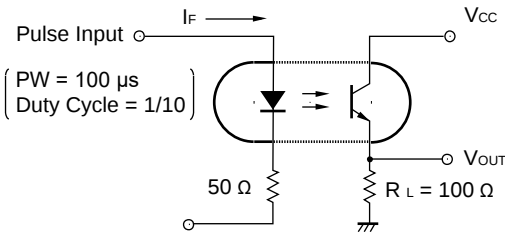
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

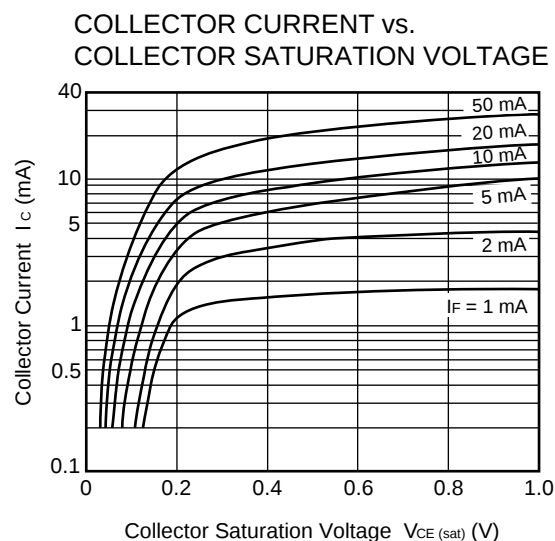
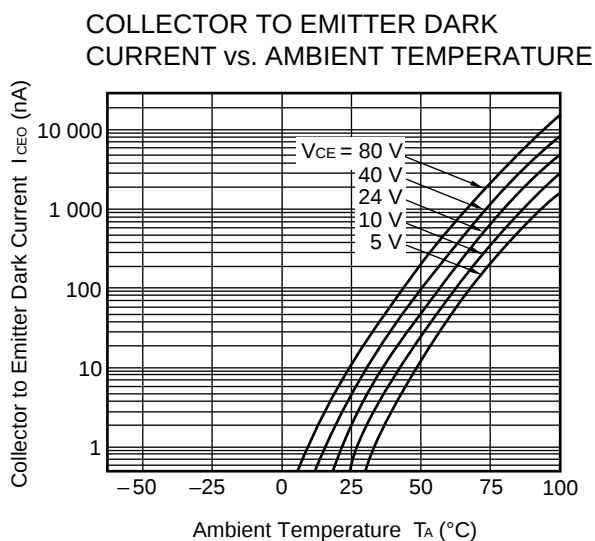
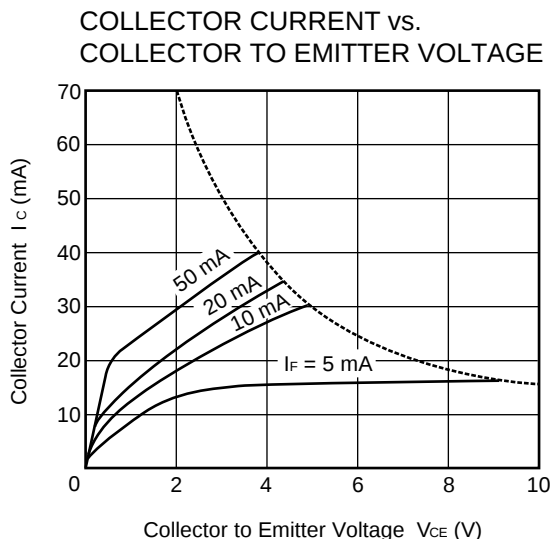
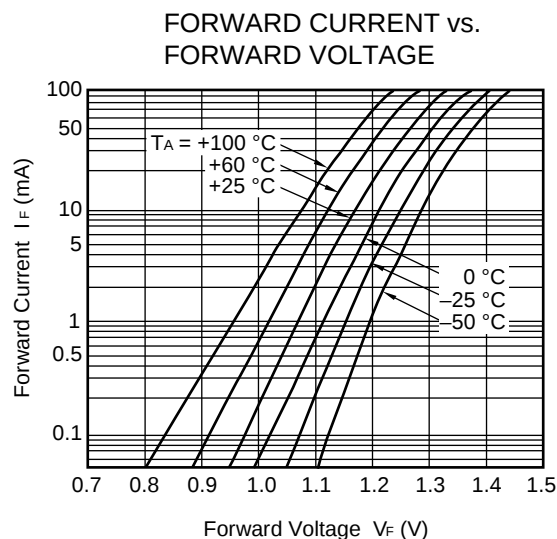
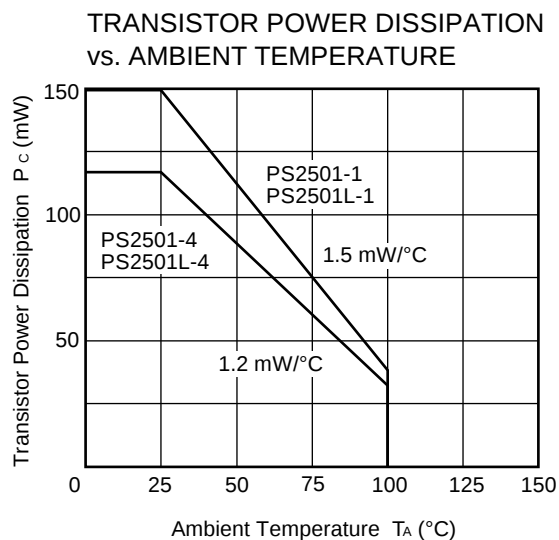
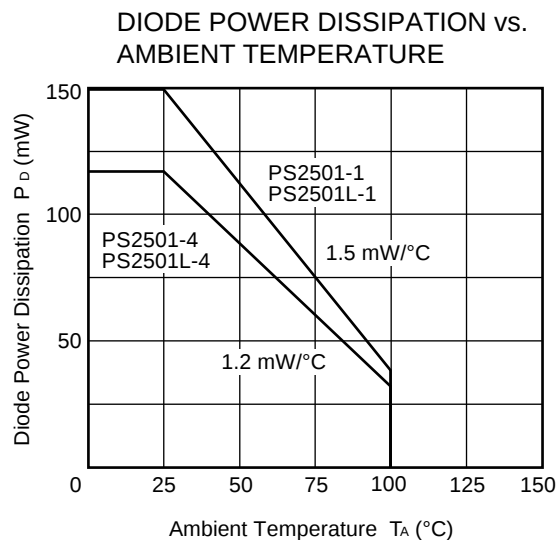
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 10 mA		1.17	1.4	V
	Reverse Current	I _R	V _R = 5 V			5	μA
	Terminal Capacitance	C _t	V = 0 V, f = 1.0 MHz		50		pF
Transistor	Collector to Emitter Dark Current	I _{CEO}	V _{CE} = 80 V, I _F = 0 mA			100	nA
Coupled	Current Transfer Ratio (I _c /I _F) *1	CTR	I _F = 5 mA, V _{CE} = 5 V	80	300	600	%
	Collector Saturation Voltage	V _{CE(sat)}	I _F = 10 mA, I _c = 2 mA			0.3	V
	Isolation Resistance	R _{I-O}	V _{I-O} = 1.0 kV _{bc}	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time *2	t _r	V _{CC} = 10 V, I _c = 2 mA, R _L = 100 Ω		3		μs
	Fall Time *2	t _f			5		

Note : *1. CTR rank (* : only PS2501-1, PS2501L-1)

- K* : 300 to 600 (%)
- L* : 200 to 400 (%)
- M* : 80 to 240 (%)
- D* : 100 to 300 (%)
- H* : 80 to 160 (%)
- W* : 130 to 260 (%)
- Q* : 100 to 200 (%)
- N : 80 to 600 (%)

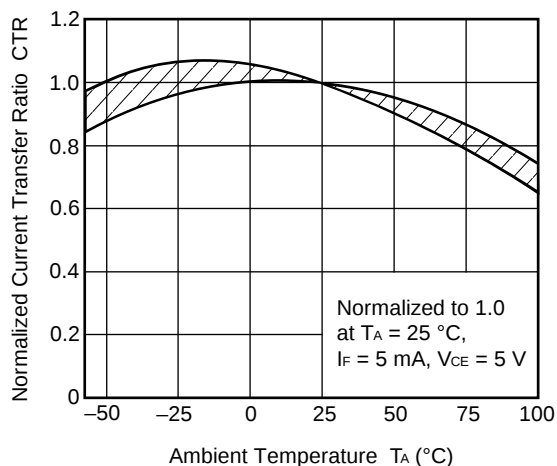
*2. Test Circuit for Switching Time



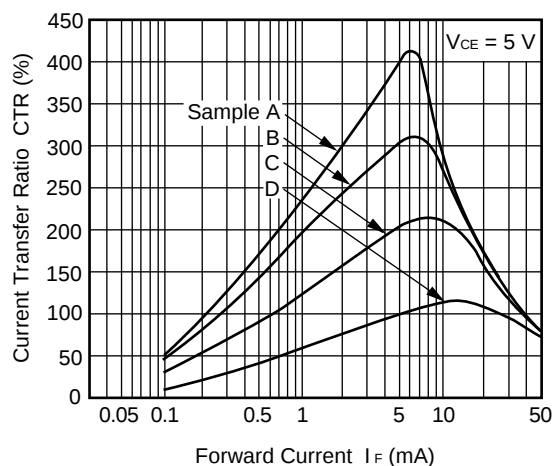
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Remark The graphs indicate nominal characteristics.

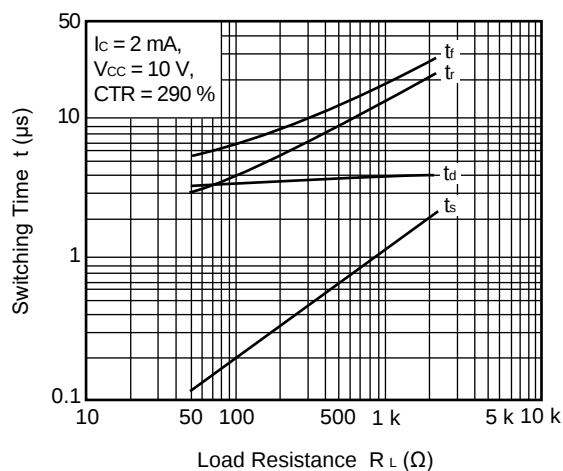
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



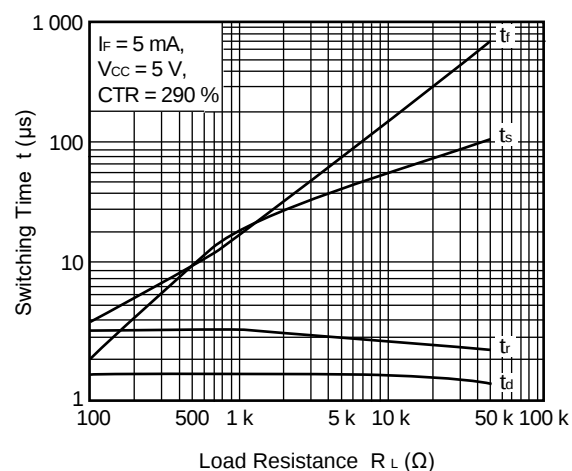
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



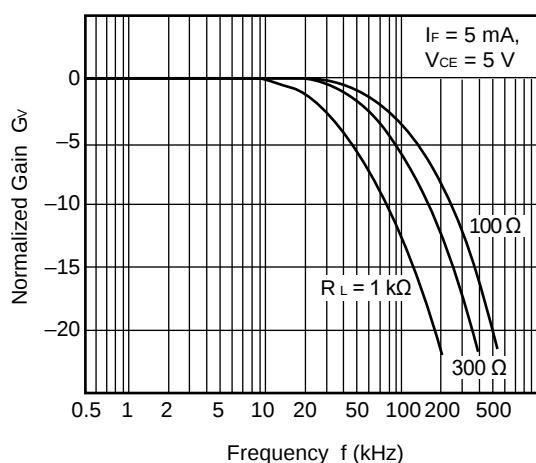
SWITCHING TIME vs. LOAD RESISTANCE



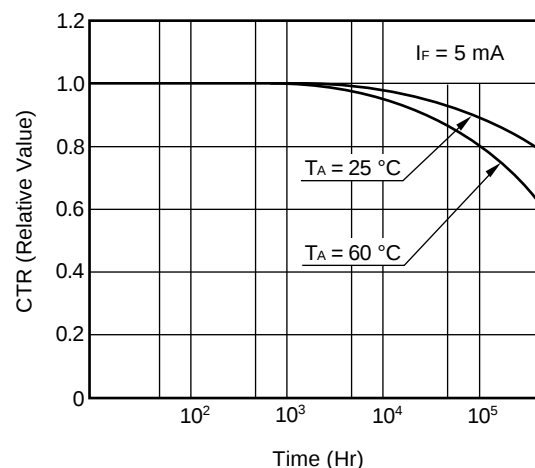
SWITCHING TIME vs. LOAD RESISTANCE



FREQUENCY RESPONSE



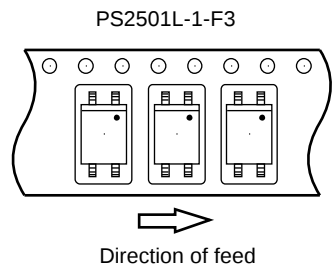
LONG TERM CTR DEGRADATION



Remark The graphs indicate nominal characteristics.

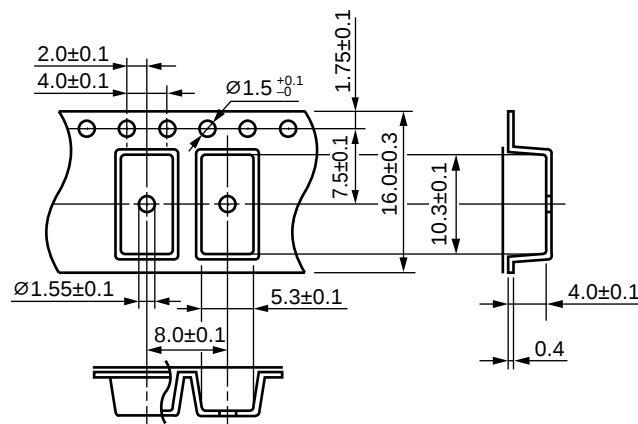
TAPING SPECIFICATIONS (UNIT: mm)

Tape Direction



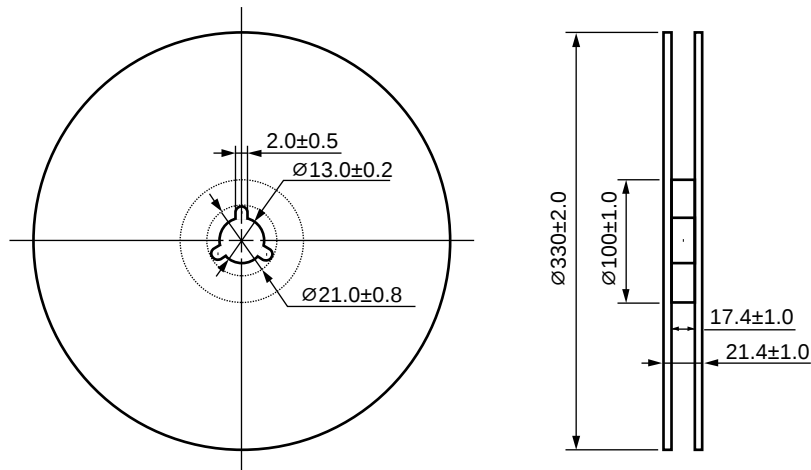
Outline and Dimensions (Tape)

Unit : mm



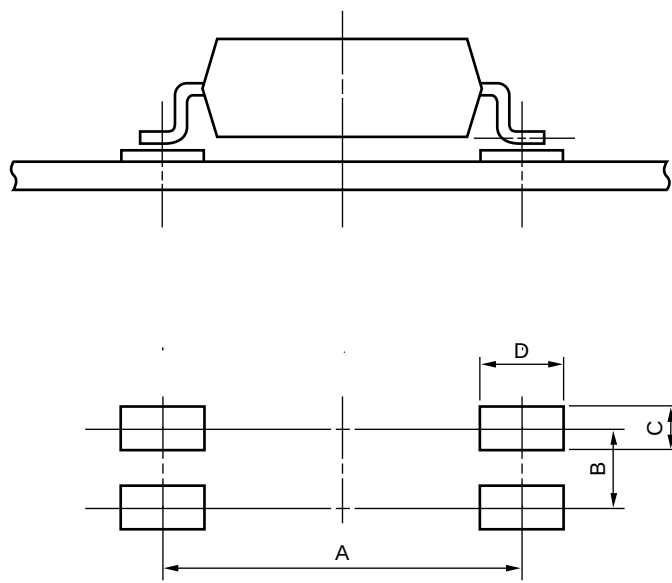
Outline and Dimensions (Reel)

Unit : mm



Packing: 2 000 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Part Number	Lead Bending	A	B	C	D
PS2501L	Lead Bending Type For Surface Mount	8.2	2.54	1.7	2.2

Remark All dimensions in this figure must be evaluated before use.

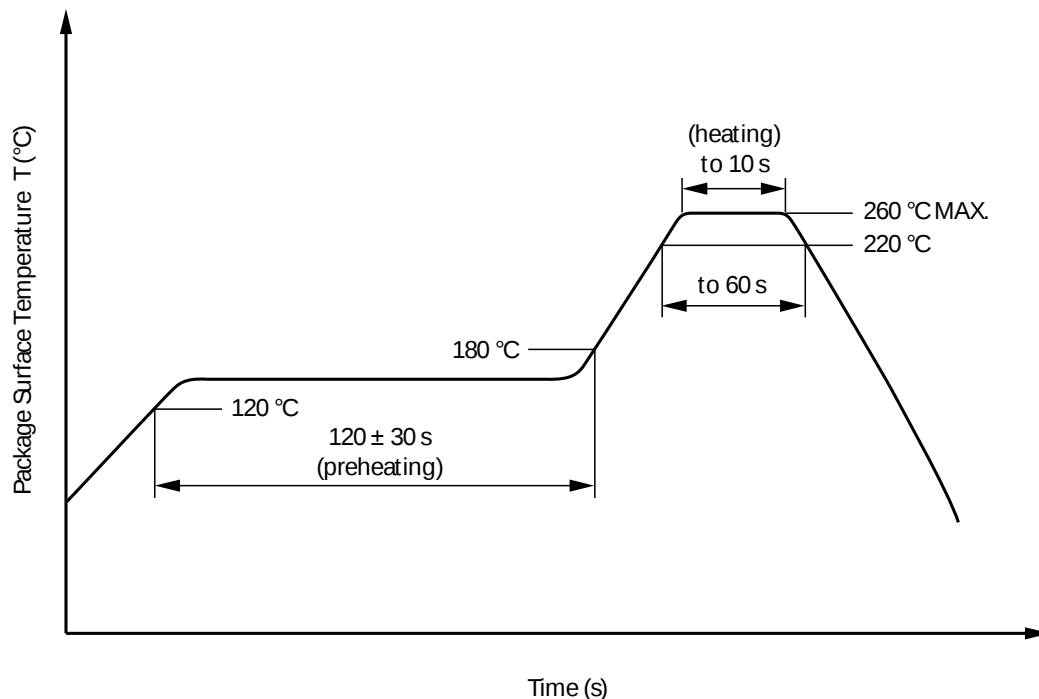
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260 °C or below (package surface temperature)
- Time of peak reflow temperature 10 s or less
- Time of temperature higher than 220 °C 60 s or less
- Time to preheat temperature from 120 to 180 °C 120 ± 30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260 °C or below (molten solder temperature)
- Time 10 s or less
- Preheating conditions 120 °C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

- Peak temperature (lead part temperature) 350 °C or below
- Time (per one side) 3 s or less
- Flux Rosin flux containing small amount of chlorine
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)
- Place 1.5 to 2.0 mm or more away from the root of the lead

(4) Cautions

- Flux cleaning Avoid cleaning with Freon- or halogen-based (chlorinated etc.) solvents.
- Fixing/Coating Do not use fixing agents or coatings containing halogen-based substances.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. This tendency may sometimes be obvious, especially below $I_F = 1$ mA.

Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.
3. Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
4. Do not use fixing agents or coatings containing halogen-based substances.

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